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Performance guide for single- and double-sided flexible printed wiring boards

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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PERFORMANCE GUIDE FOR SINGLE- AND DOUBLE-SIDED FLEXIBLE PRINTED WIRING BOARDS

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Following publication of this PAS, the technical committee or subcommittee concerned will investigate the possibility of transforming the PAS into an International Standard

This PAS shall remain valid for an initial maximum period of three years starting from 2007-04. The validity may be extended for a single three-year period, following which it shall be revised to become another type of normative document or shall be withdrawn.

PERFORMANCE GUIDE FOR SINGLE- AND DOUBLE-SIDED FLEXIBLE PRINTED WIRING BOARDS

1 Scope

This PAS provides the requirements for the single- and double-sided flexible printed wiring boards (hereinafter designated as "flexible printed board" or FPC).

In this document, an FPC means a single- or double-sided FPC prepared by lamination of a film of polyester or polyimide with copper foil(s) on one or both sides of a board including the type with no adhesive layer, and with conductor pattern formed by the subtractive method (etching of the copper foil), or possibly by the build-up method.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60326-7:1981, *Printed boards – Part 7: Specification for single- and double-sided flexible printed boards without through connections*

IEC 60326-8:1981, *Printed boards – Part 8: Specification for single- and double-sided flexible printed boards with through connections*

JPCA-TD01:2000, *Terms and definitions for printed circuits*

JPCA-BM03:2003*, Flexible printed wiring boards (adhesive and adhesiveless types)*

JIS C 5016:1994, *Test methods for flexible printed wiring boards*

JIS C 5017:1994, *Single- and double-sided flexible printed wiring boards*

JIS C 5603:1993, *Terms and definitions for printed circuits*

JIS C 6471:1995, *Test methods of copper-clad laminates for flexible printed wiring boards*

JIS C 6472:1995, *Copper-clad laminates for flexible printed wiring boards (polyester film, polyimide film)*

JIS C 6515:1998, *Copper foil for printed wiring boards*